

Simplified Process of In-Ga-Zn-O Thin Film Transistor Utilizing Selective Etching of Copper Source and Drain

Rauf Khan, Reiji Hattori

Department of Applied Science for Electronics and Materials, Kyushu University

1 Introduction:

Features of Display:

1. High resolution
2. Increasing display Size.

Challenges:

1. Reduce energy consumption.
2. Reduce RC delay.
3. Avoid image distortion and shading.

Solution: Low resistive metal (Cu) for Source and drain electrode

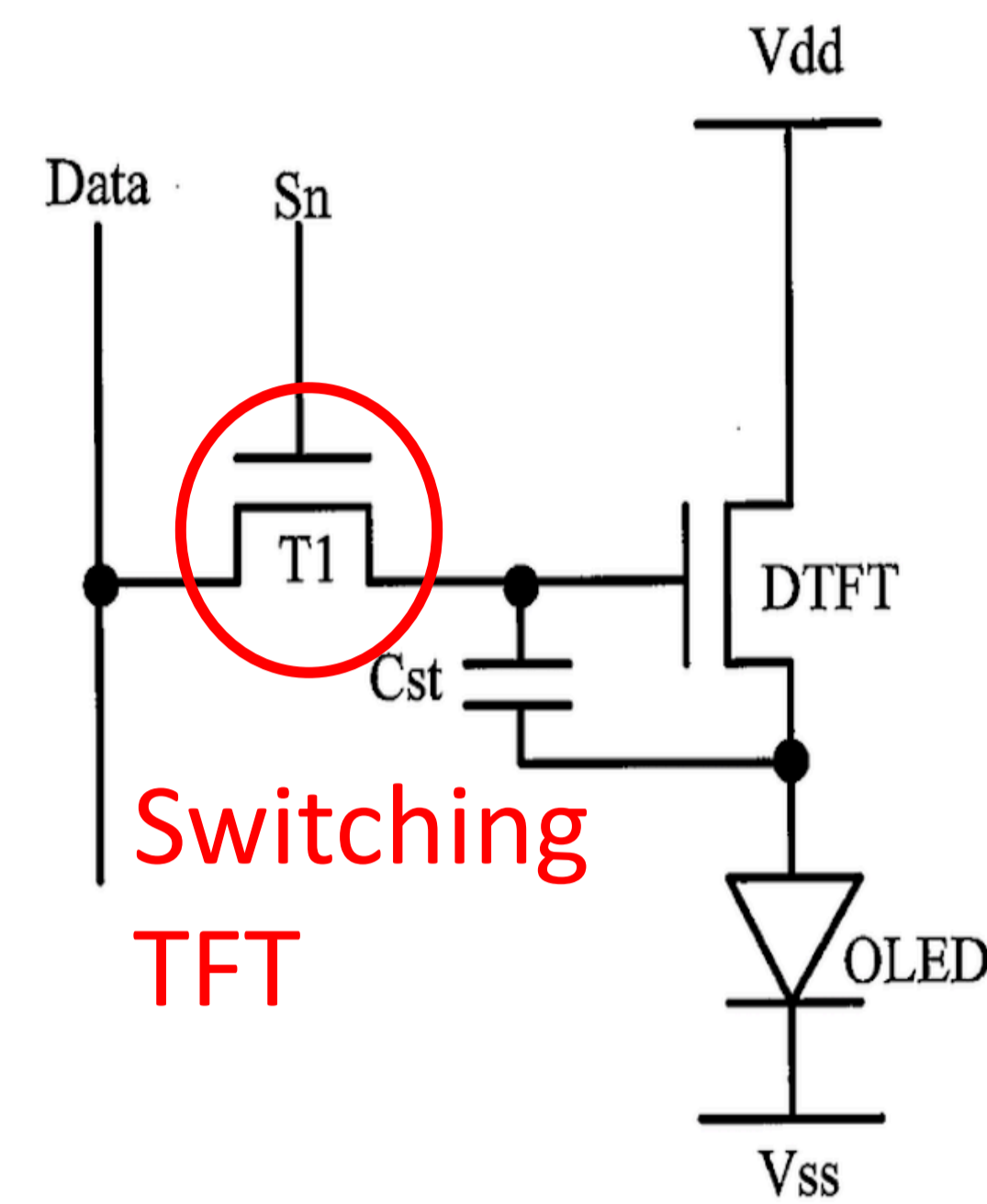


Fig. 1 : Pixel Circuit

2 Design of the proposed Device

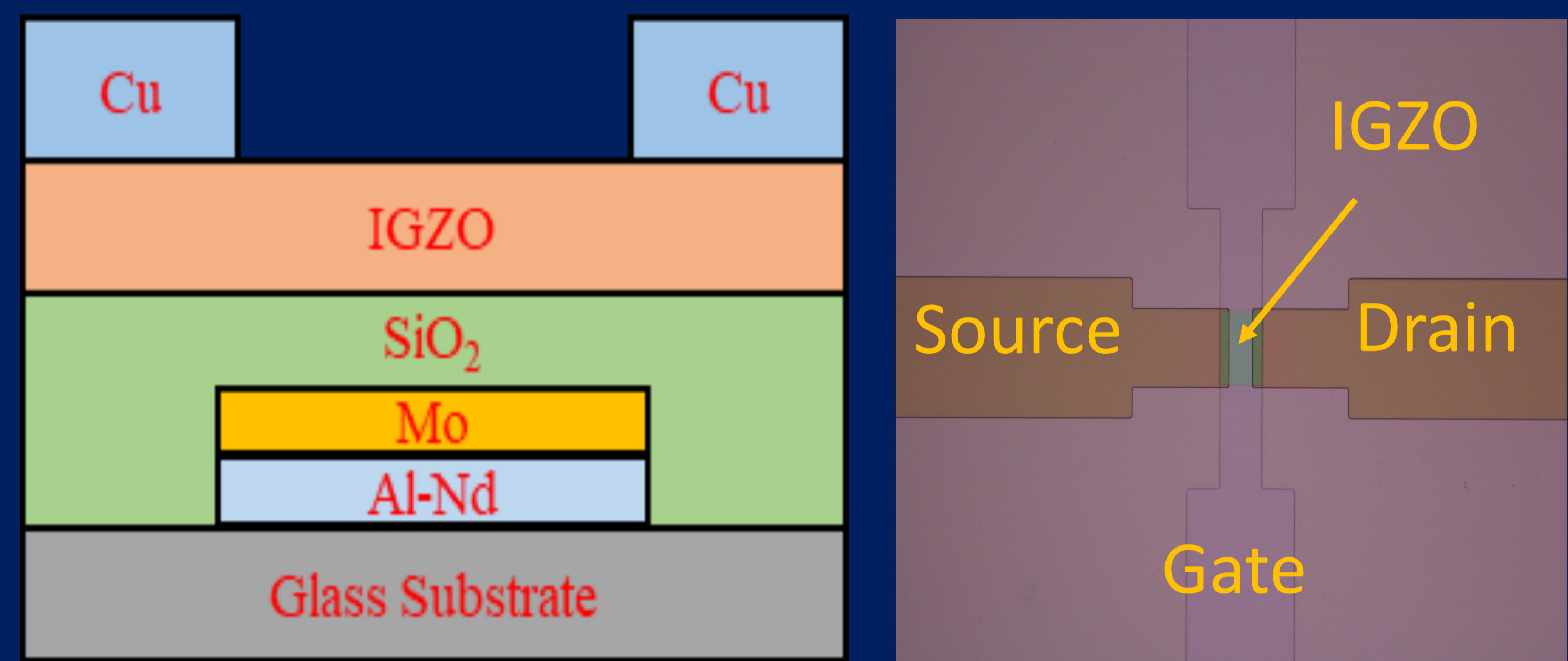


Fig. 2 : (a) Schematic diagram and (b) top view of IGZO TFT

3 Fabrication Process

- (1) Gate (Al-Nd/Mo) deposition by DC Sputtering
- (2) Gate patterning (Mask 1)
- (3) SiO₂ (gate insulator) and IGZO (active layer) deposition by CVD and DC sputtering
- (4) IGZO patterning by wet process (Mask 2) and then anneal at 300 °C for 1H at N₂
- (5) Cu deposition by thermal evaporation and patterning (Mask 3) with selective Cu etchant

4 Results & Discussion:

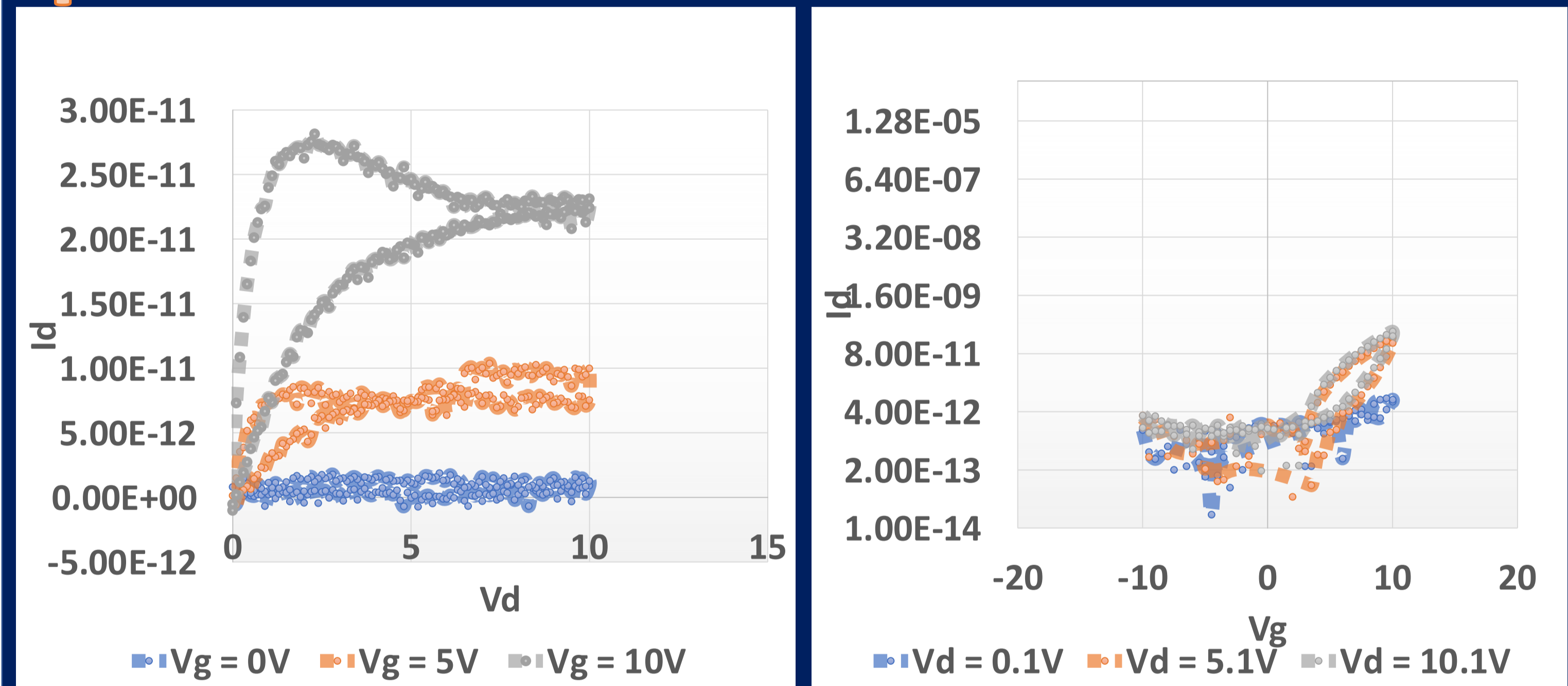


Fig. 3 (a) & (b): Output and transfer characteristics of IGZO [PO₂=1%] TFT.

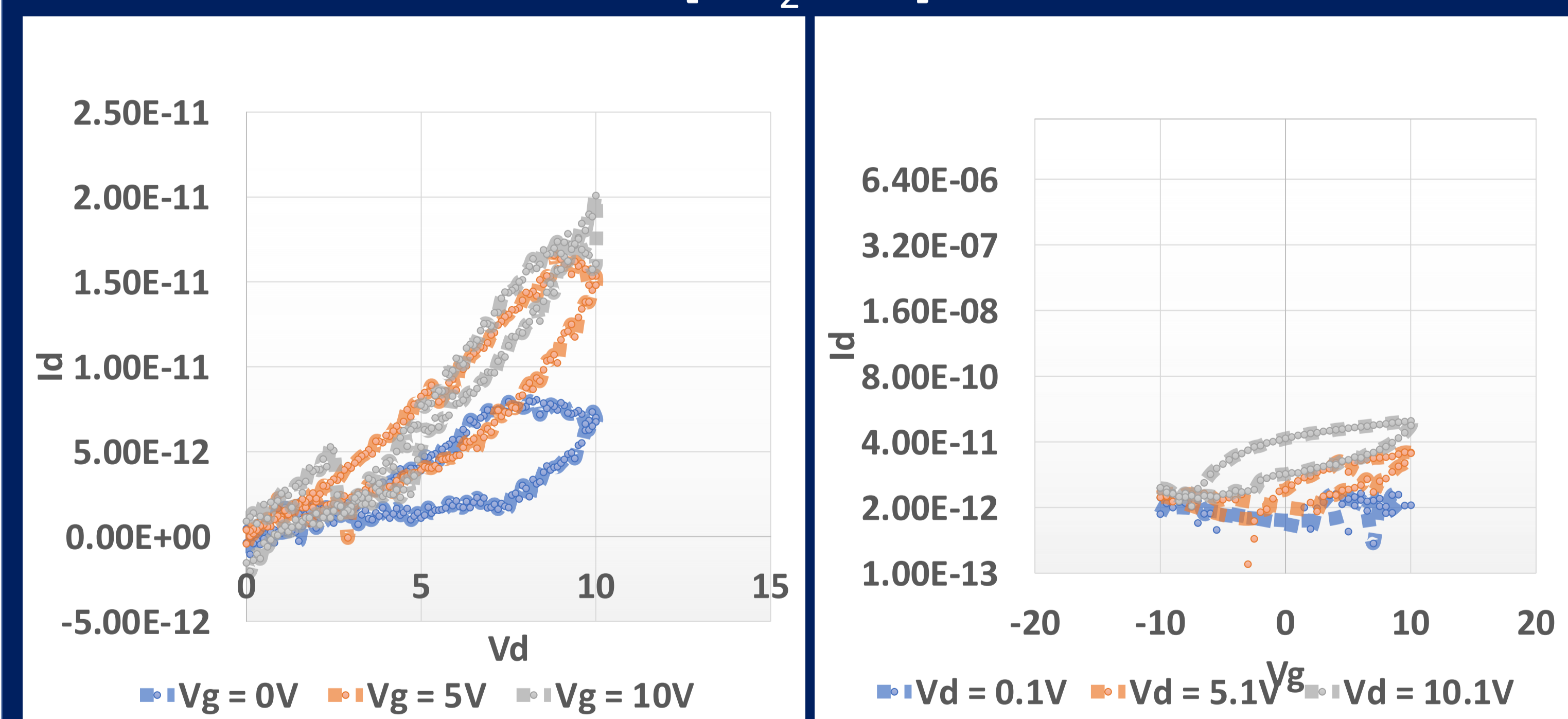


Fig. 3 (c) & (d): Output and transfer characteristics of IGZO [PO₂=5%] TFT.

5 Conclusion

- A proposed IGZO thin-film transistor fabricated successfully although the device performance is not in satisfactory level.
- Further improvement is needed to enhance device performance.

K. Nomura, H. Ohta, A. Takagi, T. Kamiya, M. Hirano, and H. Hosono, "Room-temperature fabrication of transparent flexible thin-film transistors using amorphous oxide semiconductors," *Nature*, 2004.

L. Lan *et al.*, "Influence of source and drain contacts on the properties of the indium-zinc oxide thin-film transistors based on anodic aluminum oxide gate dielectrics," in *Journal of Applied Physics*, 2011.